

**NONPROVISIONAL PATENT
APPLICATION TRANSMITTAL RULE §1.53(b)
IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Customer No. 004372

AREN'T FOX KINTNER PLOTKIN & KAHN, PLLC
1050 Connecticut Avenue, N.W.,
Suite 400
Washington, DC 20036-5339
Telephone: (202) 857-6000
Facsimile: (202) 638-4810

Docket No. 108384-00034

Date: November 30, 2001

Commissioner for Patents
Washington, D.C. 20231

Sir:

Transmitted herewith for filing under 37 C.F.R. §1.53(b) is a nonprovisional patent application:

For (Title): RESIN COMPOUND FOR FABRICATING INTERLAYER DIELECTRIC OF PRINTED WIRING BOARD, RESIN SHEET AND RESIN APPLIED-COPPER FOIL FOR FORMING INSULATING LAYER USING THE RESIN COMPOUND, AND COPPER-CLAD LAMINATE USING THEM

By (Inventors): Tetsuro SATO and Tsutomu ASAI

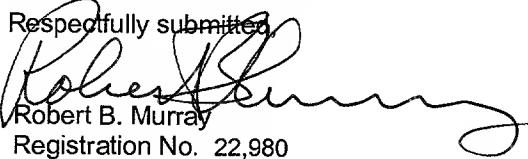
- 33 pages of Specification/Claims 1-12/Abstract are attached.
- A Declaration and Power of Attorney is attached.
- An assignment of the invention to Mitsui Mining & Smelting Co., Ltd. is attached, along with Form PTO-1595 and a check for \$40.00.
- A Preliminary Amendment is attached.
- Priority of foreign application No. 2000-374070 filed December 8, 2000 in Japan is claimed under 35 U.S.C. §119.
- A certified copy of the above corresponding foreign application is attached.

The filing fee is calculated below and includes claim status after entry of any Preliminary Amendment noted above:

FOR:	NO. FILED	NO. EXTRA
BASIC FEE		
TOTAL CLAIMS	12 - 20	= 0
INDEP CLAIMS	1 - 3	= 0
<input type="checkbox"/> MULTIPLE DEPENDENT CLAIMS		

SMALL ENTITY		LARGE ENTITY	
RATE	FEE	RATE	FEE
	\$ 370		\$ 740
x 9 =	\$	x 18	\$
x 42 =	\$	x 84	\$
+140 =	\$	+280	\$
TOTAL	\$	TOTAL	\$ 740

- A check in the amount of \$780.00 (\$740.00 for the filing fee and \$40.00 for the Assignment Recordation Fee) is attached. Please charge any fee deficiency or credit any overpayment to Deposit Account No. 01-2300.

Respectfully submitted,

 Robert B. Murray
 Registration No. 22,980

RBM//ars